

GaAs INTEGRATED CIRCUIT

μ PG2250T5N

1.8 V, POWER AMPLIFIER FOR Bluetooth™ Class 1

DESCRIPTION

The μ PG2250T5N is a GaAs MMIC for power amplifier which was developed for Bluetooth Class 1.

This device realizes high efficiency, high gain and high output power.

This device is housed in a 6-pin plastic TSON (Thin Small Qut-line Non-leaded) package. And this package is able to high-density surface mounting.

FEATURES

 Operating frequency : fopt = 2 400 to 2 500 MHz (2 450 MHz TYP.) · Supply voltage : VDD1, 2, 3 = 1.5 to 3.5 V (1.8 V TYP.) : $V_{cont} = 1.5 \text{ to } 2.1 \text{ V } (1.8 \text{ V TYP.})$ Control voltage

: IDD = 100 mA TYP. @ VDD1, 2, 3 = 1.8 V, Vcont = 1.8 V, Pout = +19 dBm Circuit current : Pout = +20.0 dBm TYP. @ VDD1, 2, 3 = 1.8 V, Vcont = 1.8 V, Pin = -5 dBm· Output power Gain control range : GCR = 60 dB TYP. @ V_{DD1} , 2, 3 = 1.8 V, V_{cont} = 0 to 1.8 V, P_{in} = -5 dBm : PAE = 55% TYP. @ VDD1, 2, 3 = 1.8 V, Vcont = 1.8 V, Pin = -5 dBm High efficiency

High-density surface mounting : 6-pin plastic TSON package ($1.5 \times 1.5 \times 0.37$ mm)

APPLICATION

· Power Amplifier for Bluetooth Class 1

ORDERING INFORMATION

Part Number	Order Number	Package	Marking	Supplying Form
μPG2250T5N-E2	μPG2250T5N-E2-A	6-pin plastic TSON (Pb-Free)	G5C	 Embossed tape 8 mm wide Pin 1, 6 face the perforation side of the tape Qty 3 kpcs/reel

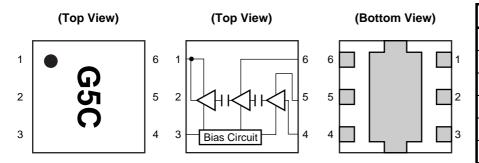
Remark To order evaluation samples, contact your nearby sales office.

Part number for sample order: µPG2250T5N-A

Caution Observe precautions when handling because these devices are sensitive to electrostatic discharge.

The information in this document is subject to change without notice. Before using this document, please confirm that this is the latest version.

PIN CONNECTIONS AND INTERNAL BLOCK DIAGRAM



Pin No.	Pin Name	
1	OUTPUT/V _{DD} 3	
2	N.C.	
3	V _{cont}	
4	INPUT	
5	V _{DD} 1	
6 V _{DD} 2		

Remark Exposed pad: GND

ABSOLUTE MAXIMUM RATINGS (Ta = +25°C, unless otherwise specified)

Parameter	Symbol	Ratings	Unit
Supply Voltage	V _{DD} 1, 2, 3	5.0	V
Control Voltage	Vcont	2.4	V
Circuit Current	IDD	250	mA
Control Current	Icont	5	mA
Input Power	Pin	+5	dBm
Power Dissipation	Po	400 Note	mW
Operating Ambient Temperature	TA	-40 to +85	°C
Storage Temperature	T _{stg}	–55 to +150	°C

Note Mounted on double-sided copper-clad $50 \times 50 \times 1.6$ mm epoxy glass PWB, T_A = +85°C

RECOMMENDED OPERATING RANGE (TA = +25°C, unless otherwise specified)

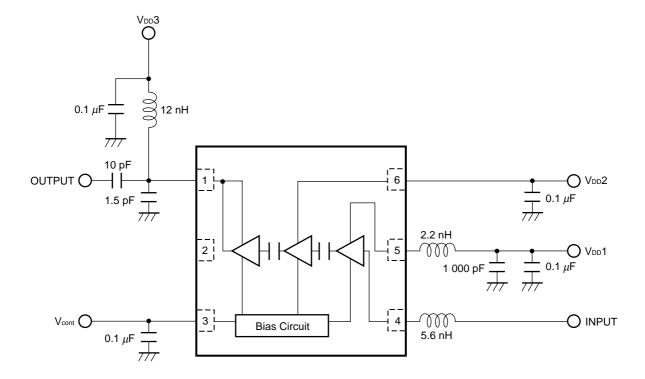
Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Operating Frequency	f _{opt}	2 400	2 450	2 500	MHz
Supply Voltage	V _{DD} 1, 2, 3	1.5	1.8	3.5	٧
Control Voltage	Vcont	1.5	1.8	2.1	V

ELECTRICAL CHARACTERISTICS

(TA = +25°C, VDD1, 2, 3 = 1.8 V, f = 2 450 MHz, Pout = +19 dBm, external input and output matching, unless otherwise specified)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Circuit Current	IDD	V _{cont} = 1.8 V, P _{out} = +19 dBm	-	100	130	mA
Control Current	Icont	V _{cont} = 1.8 V, P _{out} = +19 dBm	=	=	3	mA
Shut Down Current	shut down	V _{cont} = 0 V, RF None	=	=	5	μА
Output Power 1	Pout1	V _{cont} = 1.8 V, P _{in} = -5 dBm	+19.0	+20.0	=	dBm
Output Power 2	Pout2	V _{cont} = 0 V, P _{in} = -5 dBm	-	-40.0	_	dBm
Gain Control Range	GCR	$V_{cont} = 0$ to 1.8 V, $P_{in} = -5$ dBm	=	60	=	dB
Efficiency	PAE	V _{cont} = 1.8 V, P _{in} = -5 dBm	=	55	=	%
2nd Harmonics	2f ₀	V _{cont} = 1.8 V, P _{in} = -5 dBm	1	35	l	dBc

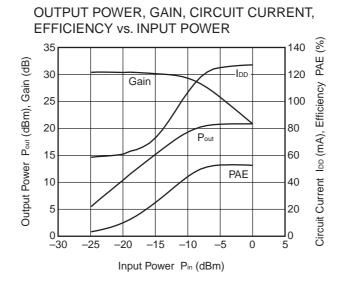
EVALUATION CIRCUIT



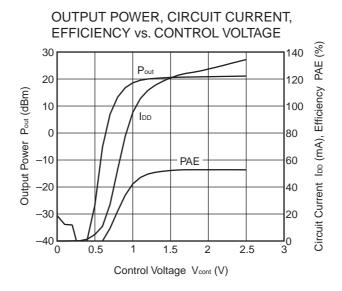
The application circuits and their parameters are for reference only and are not intended for use in actual design-ins.

TYPICAL CHARACTERISTICS (TA = +25°C, unless otherwise specified)

Condition: f = 2 450 MHz, VDD1 = VDD2 = VDD3 = Vcont = 1.8 V, with external input and output matching circuits



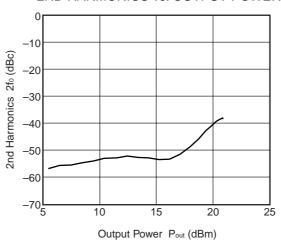
Condition : f = 2 450 MHz, $V_{DD}1 = V_{DD}2 = V_{DD}3 = V_{cont} = 1.8 \text{ V}$, $P_{in} = -5 \text{ dBm}$, with external input and output matching circuits



Remark The graphs indicate nominal characteristics.

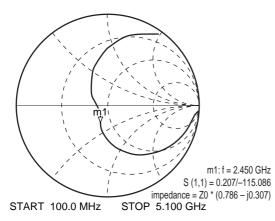
Condition: f = 2 450 MHz, VDD1 = VDD2 = VDD3 = Vcont = 1.8 V, with external input and output matching circuits

2ND HARMONICS vs. OUTPUT POWER

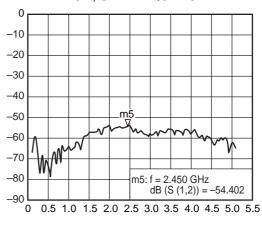


Condition: VDD1 = VDD2 = VDD3 = Vcont = 1.8 V, with external input and output matching circuits

S₁₁-FREQUENCY



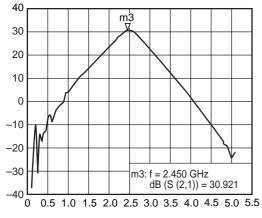
S₁₁, S₂₂-FREQUENCY



Frequency f (GHz)

S22-FREQUENCY

S₂₁-FREQUENCY



Frequency f (GHz)

m7:f = 2.450 GHz

impedance = Z0 * (0.352 - j0.123) START 100.0 MHz STOP 5.100 GHz

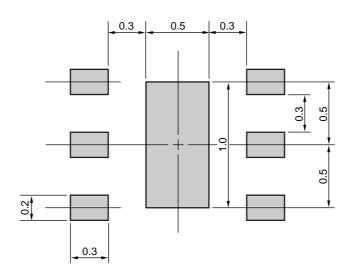
S (2,2) = 0.486/-164.104

Remark The graphs indicate nominal characteristics.

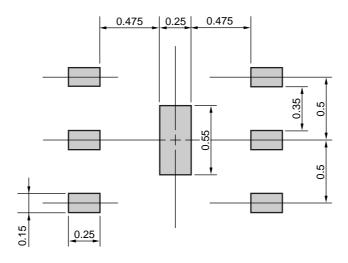
MOUNTING PAD AND SOLDER MASK LAYOUT DIMENSIONS

6-PIN PLASTIC TSON (UNIT: mm)

MOUNTING PAD



SOLDER MASK

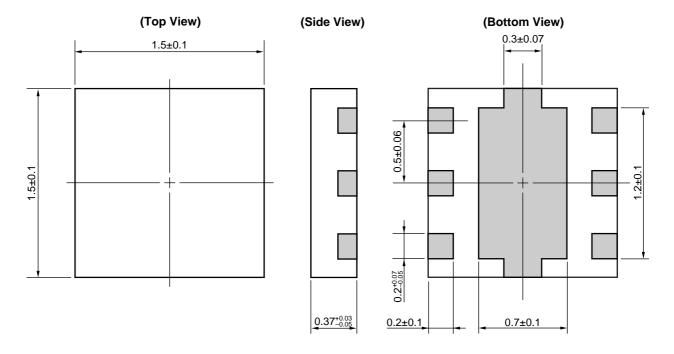


Solder thickness: 0.08 mm

Remark The mounting pad and solder mask layouts in this document are for reference only.

PACKAGE DIMENSIONS

6-PIN PLASTIC TSON (UNIT: mm)



RECOMMENDED SOLDERING CONDITIONS

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

Soldering Method	Soldering Conditions		Condition Symbol
Infrared Reflow	Peak temperature (package surface temperature) Time at peak temperature Time at temperature of 220°C or higher Preheating time at 120 to 180°C Maximum number of reflow processes Maximum chlorine content of rosin flux (% mass)	: 260°C or below : 10 seconds or less : 60 seconds or less : 120±30 seconds : 3 times : 0.2%(Wt.) or below	IR260
Wave Soldering	Peak temperature (molten solder temperature) Time at peak temperature Preheating temperature (package surface temperature) Maximum number of flow processes Maximum chlorine content of rosin flux (% mass)	: 260°C or below : 10 seconds or less : 120°C or below : 1 time : 0.2%(Wt.) or below	WS260
Partial Heating	Peak temperature (terminal temperature) Soldering time (per side of device) Maximum chlorine content of rosin flux (% mass)	: 350°C or below : 3 seconds or less : 0.2%(Wt.) or below	HS350

Caution Do not use different soldering methods together (except for partial heating).

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M8E 02.11-1

Caution

GaAs Products

This product uses gallium arsenide (GaAs).

GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.

- Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
 - Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.
- 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.
- Do not burn, destroy, cut, crush, or chemically dissolve the product.
- Do not lick the product or in any way allow it to enter the mouth.

▶ For further information, please contact

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This status is based on CEL's understanding of the EU Directives and knowledge of the materials that go into its products as of the date of disclosure of this information.

Restricted Substance per RoHS	Concentration Limit per RoHS (values are not yet fixed)		on contained devices
Lead (Pb)	< 1000 PPM	-A Not Detected	-AZ (*)
Mercury	< 1000 PPM	Not Detected	
Cadmium	< 100 PPM	Not Detected	
Hexavalent Chromium	< 1000 PPM	Not Detected	
PBB	< 1000 PPM	Not Detected	
PBDE	< 1000 PPM	Not Detected	

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